

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Tsung-Min Hsieh	01/22/2010
Chien-Hsing Lee	01/22/2010
Jhyy-Cheng Liou	01/22/2010
RECEIVING PARTY DATA	
Name:	Solid State System Co., Ltd.
Street Address:	5F-1, No. 22, Taiyuen Street,
Internal Address:	Jubei City
City:	Hsinchu
State/Country:	TAIWAN
Postal Code:	302
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12691754
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	32889-US-PA
NAME OF SUBMITTER:	Belinda Lee
Total Attachments: 2 source=32889_a#page1.tif source=32889_a#page2.tif	

CH \$40.00 12691754

ASSIGNMENT

WHEREAS,

1. Tsung-Min Hsieh
2. Chien-Hsing Lee
3. Jhyy-Cheng Liou

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **METHOD FOR FABRICATING MEMS DEVICE**

Filed: Serial No.

Executed concurrently with the execution of this instrument

WHEREAS, Solid State System Co., Ltd.

of 5F-1, No. 22, Taiyuen Street, Jubei City, Hsinchu, Taiwan 302, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Tsung-Min Hsieh
Sole or First Joint Inventor: Tsung-Min Hsieh

Date: 2010-01-22

Signature: Chien Hsing Lee
Second Joint Inventor (if any): Chien-Hsing Lee

Date: 2010-01-22

Signature: Jhy-Cheng Liou
Third Joint Inventor (if any): Jhy-Cheng Liou

Date: 2010-01-22